

Features

- Split Gate Trench MOSFET Technology
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note 1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

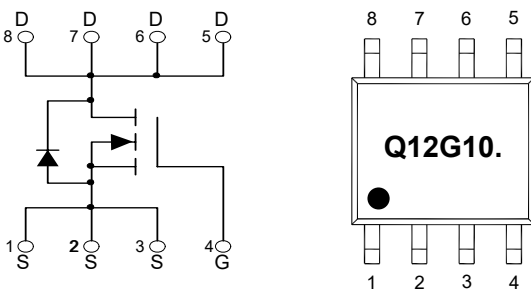
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Maximum Thermal Resistance: 60°C/W Junction to Ambient(Notes2)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V _{DS}	100	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current	I _D	T _A =25°C	12
		T _A =100°C	7.5
Pulsed Drain Current (Note3)	I _{DM}	48	A
Total Power Dissipation (Note4)	P _D	2.1	W
Avalanche Energy (Note5)	E _{AS}	80	mJ

Note:

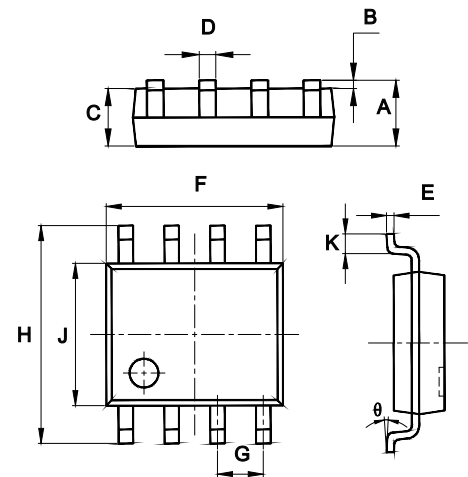
1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of R_{θJA} is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C.
3. Repetitive rating; pulse width limited by max. junction temperature.
4. P_D is based on max. junction temperature, using junction-ambient thermal resistance.
5. T_J=25°C, V_{DD}=30V, V_{GS}=10V, R_G=25Ω, L=0.5mH

Internal Structure and Marking Code



N-Channel Power MOSFET

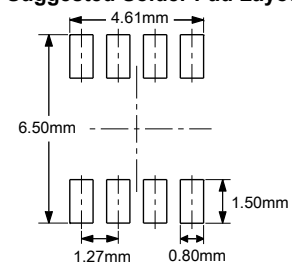
SOP-8



DIMENSIONS

DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.053	0.069	1.35	1.75	
B	0.004	0.010	0.10	0.25	
C	0.053	0.061	1.35	1.55	
D	0.013	0.020	0.33	0.51	
E	0.007	0.010	0.17	0.25	
F	0.185	0.200	4.70	5.10	
G	0.050		1.270		TYP.
H	0.228	0.244	5.80	6.20	
J	0.150	0.157	3.80	4.00	
K	0.016	0.050	0.40	1.27	
θ	0°	8°	0°	8°	

Suggested Solder Pad Layout



ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	100			V
Gate-Source Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=100V, V_{GS}=0V$			1	μA
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2	2.8	4	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=10A$		14.5	17	m Ω
Gate Resistance	R_G	f=1MHz, Open drain		1.5		Ω
Diode Characteristics						
Continuous Body Diode Current	I_S				12	A
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=12A$			1.3	V
Reverse Recovery Time	t_{rr}	$I_F=10A, dI_F/dt=100A/\mu s$		41		ns
Reverse Recovery Charge	Q_{rr}			26		nC
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=50V, V_{GS}=0V, f=1MHz$		1235		pF
Output Capacitance	C_{oss}			258		
Reverse Transfer Capacitance	C_{rss}			12		
Total Gate Charge	Q_g	$V_{DS}=50V, V_{GS}=10V, I_D=10A$		16		nC
Gate-Source Charge	Q_{gs}			6.3		
Gate-Drain Charge	Q_{gd}			2.6		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=50V, V_{GS}=10V, R_G=2.2\Omega, I_D=10A$		7		ns
Turn-On Rise Time	t_r			3		
Turn-Off Delay Time	$t_{d(off)}$			12		
Turn-Off Fall Time	t_f			4		

Curve Characteristics

Fig.1 - Typical Output Characteristics

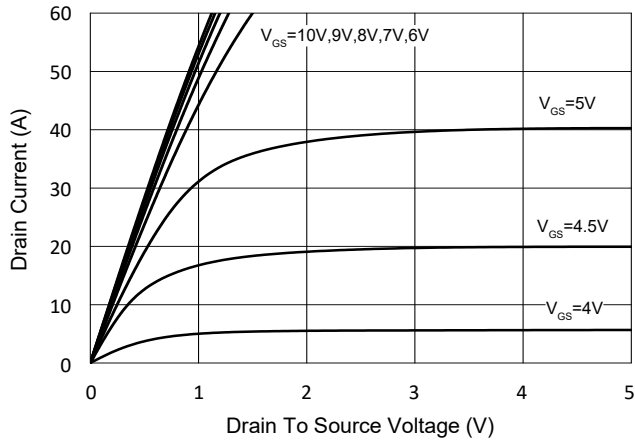


Fig.2 - Transfer Characteristic

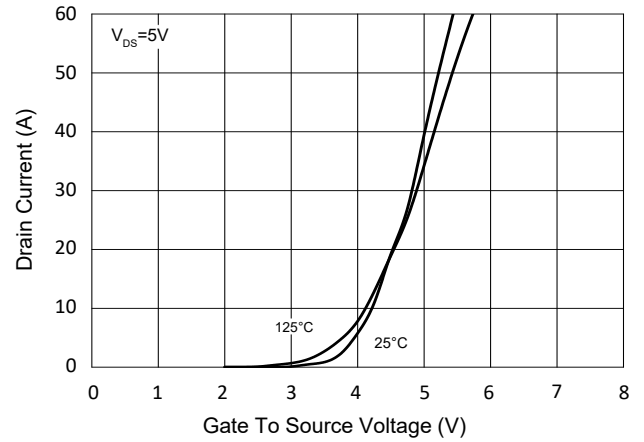


Fig.3 - $R_{DS(ON)}$ - V_{GS}

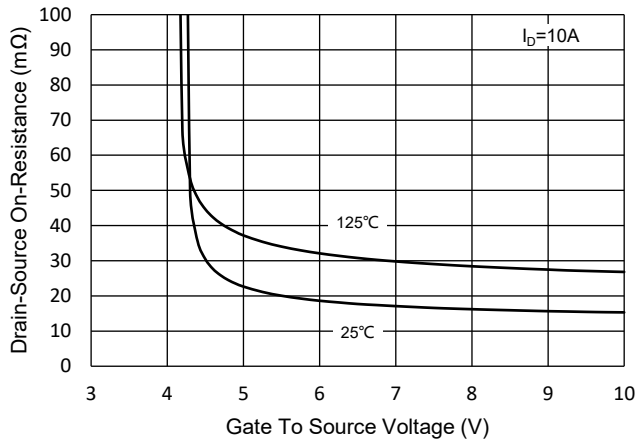


Fig.4 - $R_{DS(ON)}$ - I_D

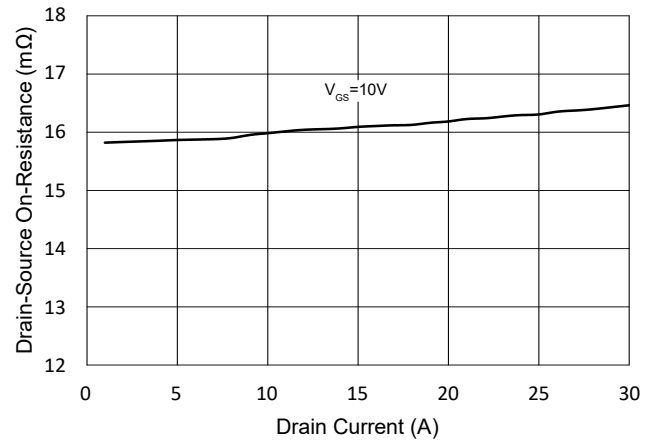


Fig.5 - Capacitance Characteristics

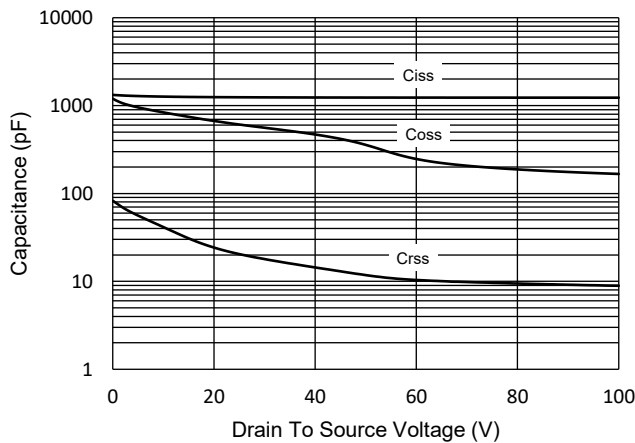
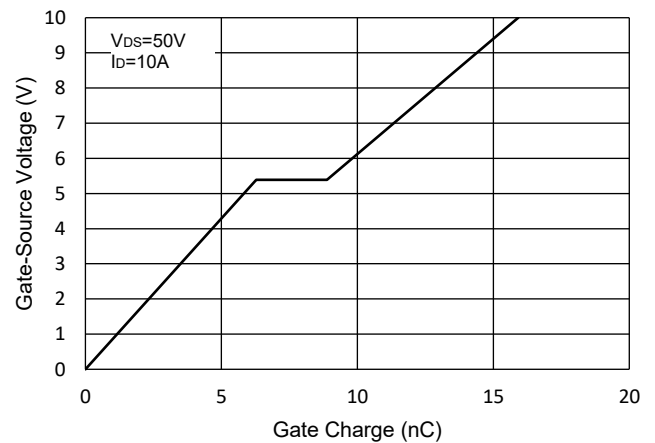


Fig.6 - Gate Charge



Curve Characteristics

Fig.7 - Normalized Threshold Voltage

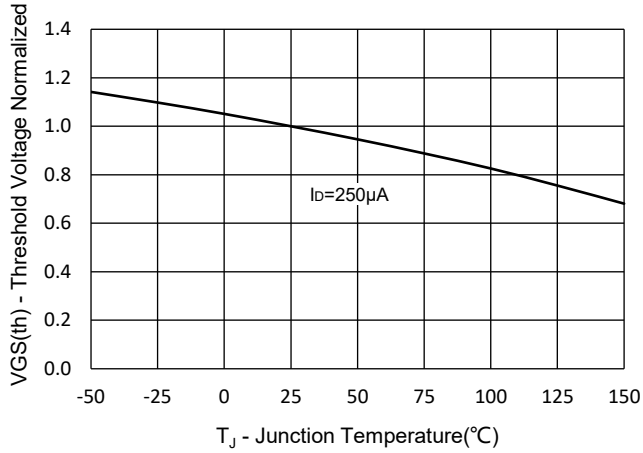


Fig.8 - Normalized On Resistance Characteristics

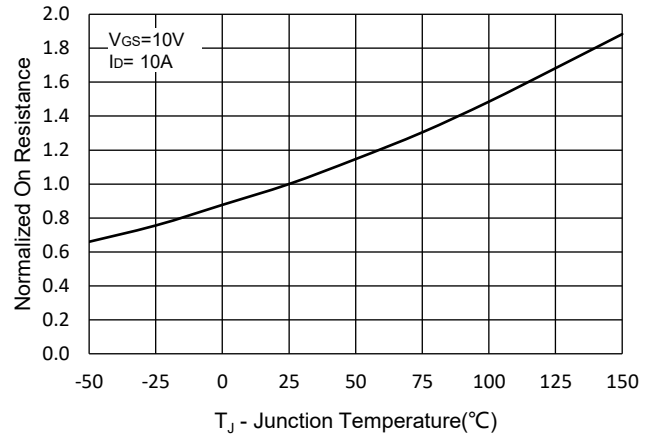


Fig.9 - $I_S - V_{SD}$

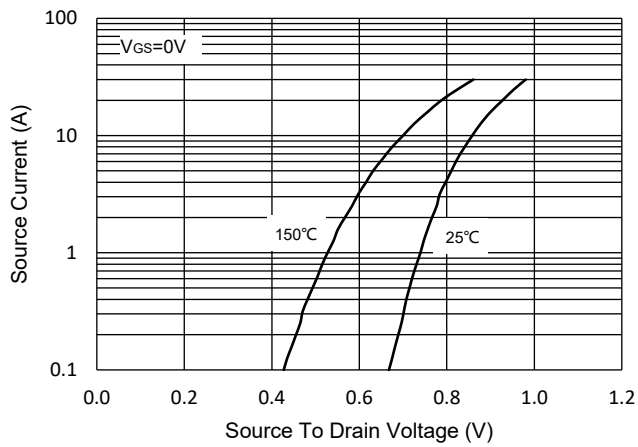


Fig.10 - Drain Current

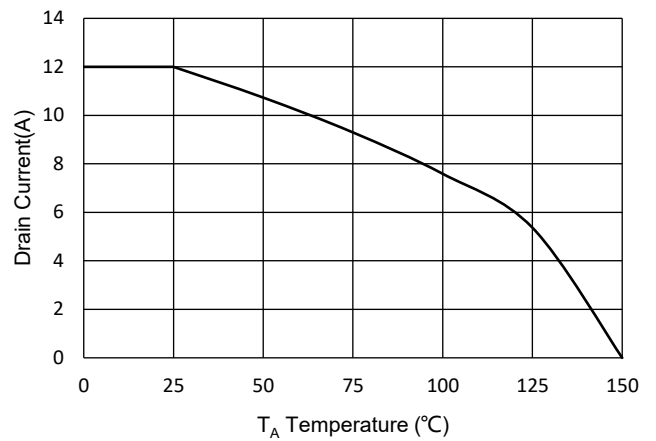
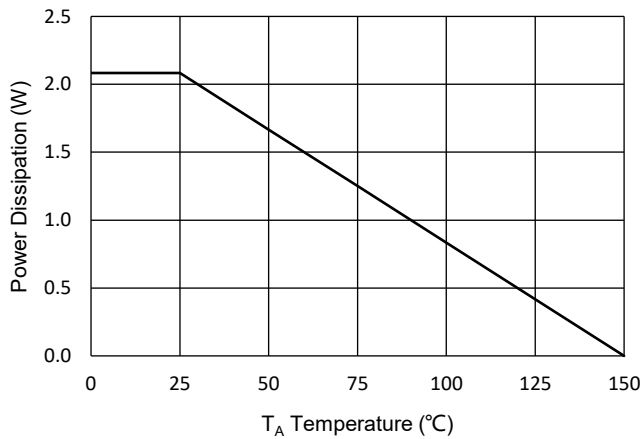


Fig.11 - PD Dissipation



Curve Characteristics

Fig.12 - Safe Operation Area

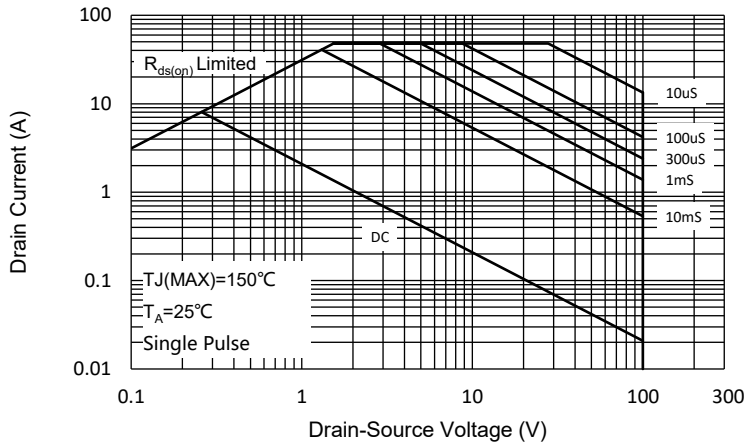
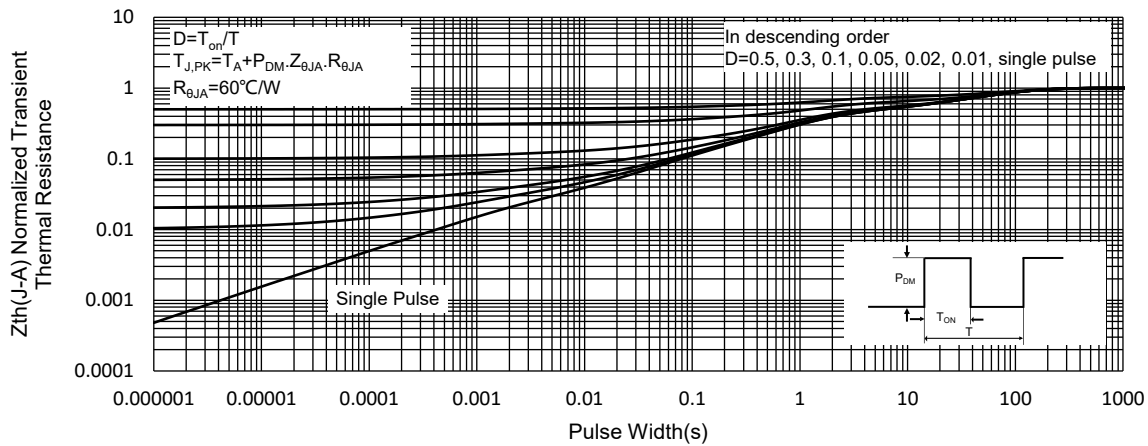


Fig.13 - Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel:4Kpcs/Reel

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